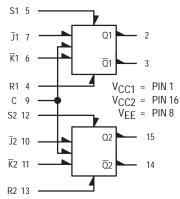
# **Dual J-K Master-Slave Flip-Flop**

The MC10H135 is a dual J–K master–slave flip–flop. The device is provided with an asynchronous set(s) and reset(R). These set and reset inputs overide the clock.

A common clock is provided with separate  $\overline{J}-\overline{K}$  inputs. When the clock is static, the  $\overline{JK}$  inputs do not effect the output. The output states of the flip flop change on the positive transition of the clock.

- Propagation delay, 1.5 ns Typical
- Power Dissipation, 280 mW Typical/Pkg. (No Load)
- ftog 250 MHz Max
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K-Compatible

## **LOGIC DIAGRAM**



#### RS TRUTH TABLE

R	S	Q <sub>n + 1</sub>
L	L	Qn
L	Н	Н
Н	L	L
Н	Н	N.D.

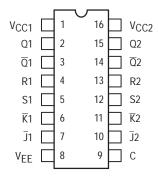
N.D. = Not Defined

# CLOCK J-K TRUTH TABLE\*

_			
	J	K	Q <sub>n + 1</sub>
	L	L	Q <sub>n</sub>
	Н	L	L
	L	Н	Н
	Н	Н	Q <sub>n</sub>

\*Output states change on positive transition of clock for  $\overline{J}$ – $\overline{K}$  input condition present.

## DIP PIN ASSIGNMENT



Pin assignment is for Dual–in–Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).



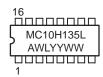
## **ON Semiconductor**

http://onsemi.com

## MARKING DIAGRAMS

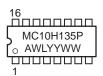


CDIP-16 L SUFFIX CASE 620





PDIP-16 P SUFFIX CASE 648





PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot YY = Year

WW = Work Week

## **ORDERING INFORMATION**

Device	Package	Shipping
MC10H135L	CDIP-16	25 Units/Rail
MC10H135P	PDIP-16	25 Units/Rail
MC10H135FN	PLCC-20	46 Units/Rail

## **MAXIMUM RATINGS**

Symbol	Characteristic	Rating	Unit	
VEE	Power Supply (V <sub>CC</sub> = 0)	-8.0 to 0	Vdc	
VI	Input Voltage (V <sub>CC</sub> = 0)	0 to VEE	Vdc	
l <sub>out</sub>	Output Current – Continuous – Surge	50 100	mA	
TA	Operating Temperature Range	0 to +75	°C	
T <sub>stg</sub>	Storage Temperature Range – Plastic – Ceramic	−55 to +150 −55 to +165	°C °C	

# **ELECTRICAL CHARACTERISTICS** ( $V_{EE} = -5.2 \text{ V} \pm 5\%$ ) (See Note 1.)

		<b>0</b> °		25°		75°		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
ΙE	Power Supply Current	_	75	_	68	-	75	mA
linH	Input Current High Pins 6, 7, 10, 11 Pins 4, 5, 12, 13 Pin 9	- - -	460 800 675		285 500 420	1 1 1	285 500 420	μΑ
li <sub>nL</sub>	Input Current Low	0.5	_	0.5	ı	0.3	-	μΑ
Vон	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
VOL	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
VIH	High Input Voltage	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V <sub>IL</sub>	Low Input Voltage	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc

## **AC PARAMETERS**

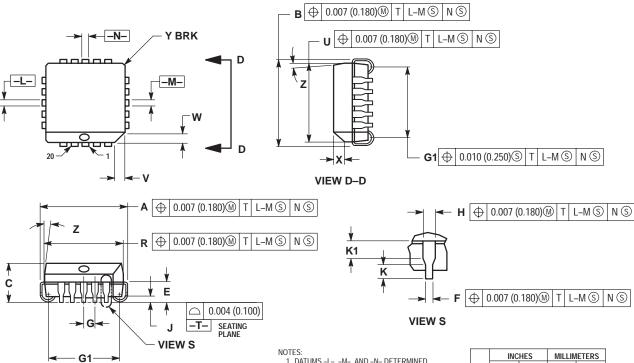
<sup>t</sup> pd	Propagation Delay Set, Reset, Clock	0.7	2.6	0.7	2.6	0.7	2.6	ns
t <sub>r</sub>	Rise Time	0.7	2.2	0.7	2.2	0.7	2.2	ns
t <sub>f</sub>	Fall Time	0.7	2.2	0.7	2.2	0.7	2.2	ns
t <sub>set</sub>	Set-up Time	1.5	-	1.5	-	1.5		ns
<sup>t</sup> hold	Hold Time	1.0	_	1.0	_	1.0	-	ns
f <sub>tog</sub>	Toggle Frequency	250	-	250	_	250	_	MHz

<sup>1.</sup> Each MECL 10H series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 lfpm is maintained. Outputs are terminated through a 50-ohm resistor to -2.0 volts.

## **PACKAGE DIMENSIONS**

## PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



## NOTES:

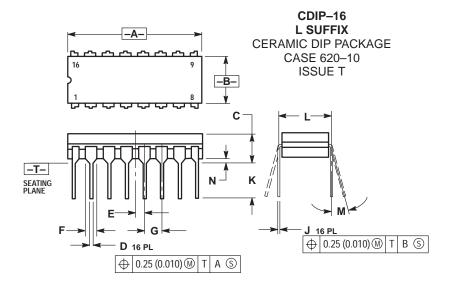
⊕ 0.010 (0.250)⑤ T L-M ⑤ N ⑤

- DATUMS -L-, -M-, AND -N- DETERMINED
   WHERE TOP OF LEAD SHOULDER EXITS PLASTIC WILLY LOVE LEAD STOUDER EXTRA FRAST BODY AT MOLD PARTING LINE.

  2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD
- FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
  4. DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. 5. CONTROLLING DIMENSION: INCH.
- 6. THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

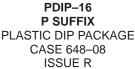
	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Х	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10 °	2 °	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

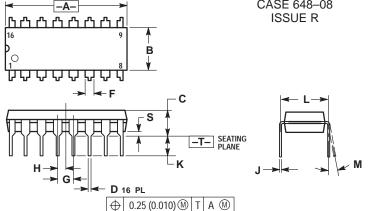


#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
  DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
  DIMENSION F MAY NARROW TO 0.76 (0.030)
- WHERE THE LEAD ENTERS THE CERAMIC

	INC	HES	MILLIN	IETERS
DIM	MIN	MIN MAX		MAX
Α	0.750	0.785	19.05	19.93
В	0.240	0.295	6.10	7.49
С		0.200		5.08
D	0.015	0.020	0.39	0.50
E	0.050	) BSC	1.27 BSC	
F	0.055	0.065	1.40	1.65
G	0.100	BSC	2.54 BSC	
Н	0.008	0.015	0.21	0.38
K	0.125	0.170	3.18	4.31
L	0.300	0.300 BSC		BSC
M	0 °	15°	0 °	15°
N	0.020	0.040	0.51	1.01





#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
- DIMENSION B DOES NOT INCLUDE MOLD FLASH.
- ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS	
DIM	MIN	MIN MAX		MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0 °	10 °	
S	0.020	0.040	0.51	1.01	

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Phone: 81-3-5740-2745 Email: r14525@onsemi.com

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